



Flash Memory Summit

# Datacenter Designs Using the EDSFF Form Factors

Mark A. Shaw

*Microsoft Azure*





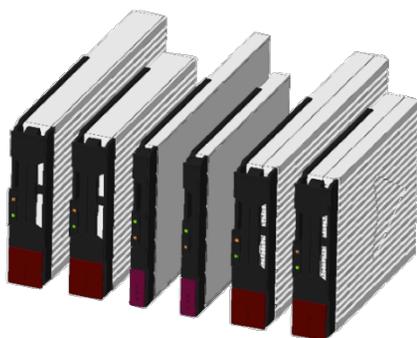
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# EDSFF – Decoupling for workloads



## SFF-TA-1006 (E1.S)

Performance Density Optimized Services  
High Power SCM (i.e. PCM/ReRAM/FRAM)  
Cache Coherent Devices (i.e. Gen-Z)  
Targets Compute nodes



## SFF-TA-1008 (E3)

Ultra High-Performance Applications  
FPGA or Computational Accelerations  
AIC / PCIe HDDL replacement



## SFF-TA-1007 (E1.L)

Capacity Density Optimized Services  
Cheapest Consumer memories (i.e. QLC)  
Denali-based pools of flash  
Targets Storage



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# Azure Design Considerations



## Performance Storage

High Density  
Low Latency  
Low \$/GB  
On-Line Service



## Compute

Increasing # of VMs per node  
Challenges keeping up with IOP Density  
Varying IOP and Density requirements  
Power, Space and Thermal constrained



## Cold Storage

High Density  
Lowest \$/GB  
Low \$/Watt  
On-Line Service



## GPU

Ultra High-Performance Applications  
FPGA or Computational Accelerations  
PCIe HHL replacement



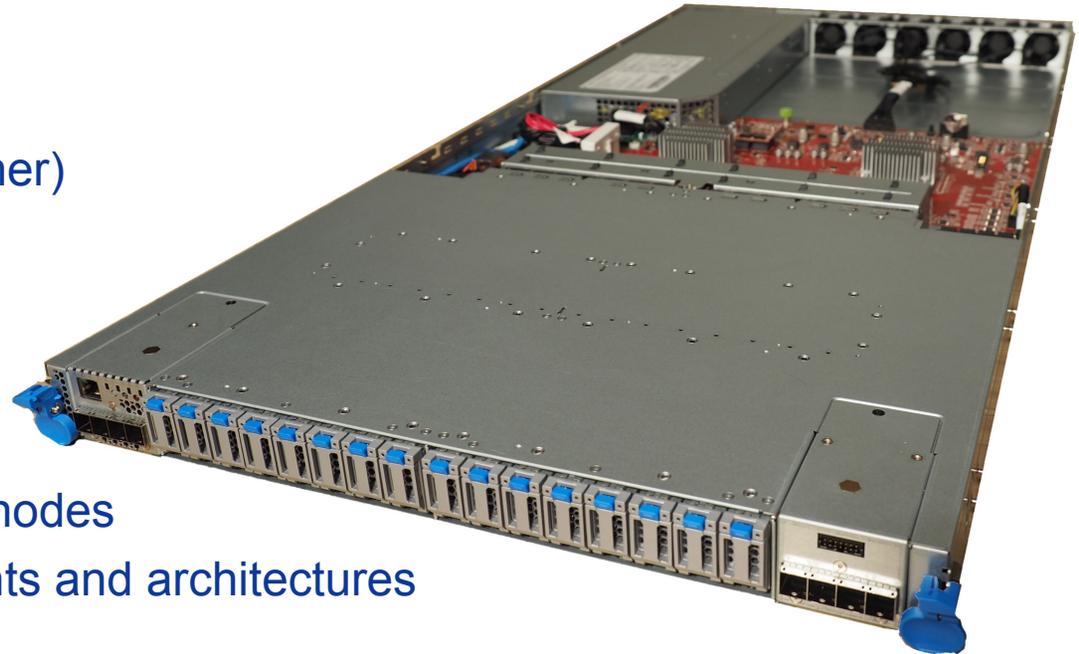
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## Performance Storage – FX16

- Lowest \$/TB
- High Density (256 TB or higher)
- Low latency
- Moderate BW/SSD
- Expandable capacity
- On-line Service
- Modular to support all head nodes
- Leverage existing components and architectures



## M.2 Carrier in FX16

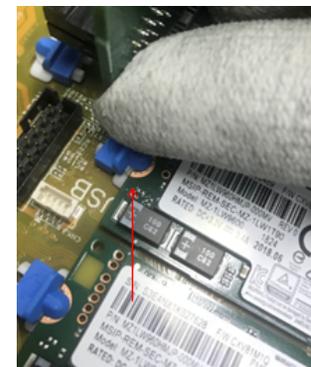


### Advantages

- TTM with existing tech
- Meets current performance requirements

### Disadvantages

- Mechanical complexity
- Thermal performance
- 3.3V power scaling
- Supply Chain complexity
- Service complexity
- Increased “spares” support
- Lack of QLC support (\$\$)



## E1.L in FX16



### Advantages

- Meets performance requirements
- Reduced mechanical complexity
- Thermal Performance
- Scalability
- Reduce Supply Chain complexity
- Reduced service complexity
- QLC support \$\$

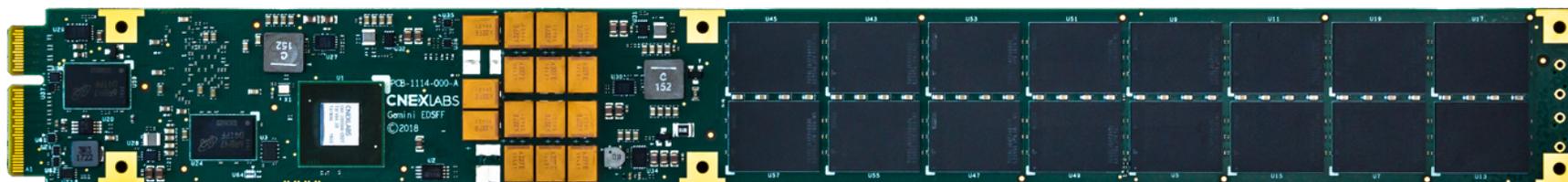
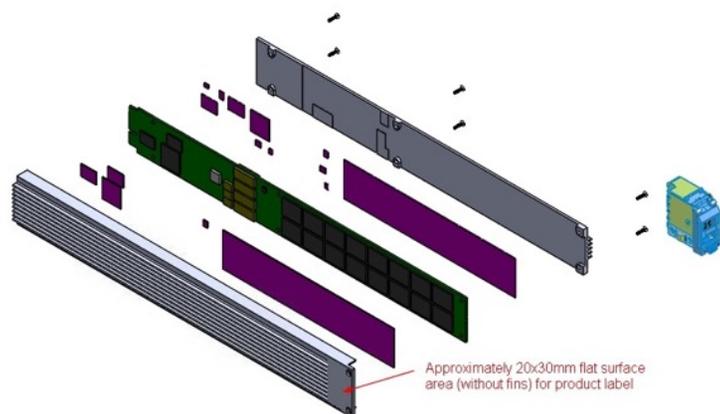
### Disadvantages

- TTM with new technology
- Risk with new technology

# Cloud SSD E1.L

## MULTI-SOURCED!!

- E1.L Form Factor
- Configurable platform for multiple work loads
- Single or Dual controller configurable
- Supports LL-NAND, eTLC, QLC
- Supports LBA and Denali Media SSD





# Going Forward

	PCIE Gen3	PCIE Gen4	PCIE Gen5
M.2		<ul style="list-style-type: none"><li>✓ Degraded connector performance</li><li>Carrier topology risks</li><li>Bent but not broken</li></ul>	<ul style="list-style-type: none"><li>✗ High risk connector performance</li><li>Higher risk carrier topologies</li><li>Likely broken</li></ul>
PCIe CEM		<ul style="list-style-type: none"><li>✓ Degraded connector performance</li><li>Reduced trace lengths</li><li>Riser topology risks</li><li>Increased board material cost</li><li>Bent but not broken</li></ul>	<ul style="list-style-type: none"><li>✗ Degraded connector performance</li><li>Reduced trace lengths</li><li>Riser topology risks</li><li>Increased board material cost</li><li>Likely broken</li></ul>
EDSFF		<ul style="list-style-type: none"><li>✓ Connector rated for Gen5</li><li>Demonstrated 2 connector topology</li></ul>	<ul style="list-style-type: none"><li>✓ Connector rated for Gen5</li><li>Demonstrated 2 connector topology</li></ul>



Thank You

